- Phase-Lock Loop Clock Driver for Synchronous DRAM and General-Purpose Applications
- Spread Spectrum Clock Compatible
- Operating Frequency: 24 MHz to 200 MHz
- Low Jitter (Cycle-cycle): <|150 ps| Over the Range 66 MHz–200 MHz
- Distributes One Clock Input to One Bank of Five Outputs (CLKOUT Is Used to Tune the Input-Output Delay)
- Three-States Outputs When There Is no Input Clock
- Operates From Single 3.3-V Supply
- Available in 8-Pin TSSOP and 8-Pin SOIC Packages
- Consumes Less Than 100 μA (Typically) in Power Down Mode
- Internal Feedback Loop Is Used to Synchronize the Outputs to the Input Clock
- 25-Ω On-Chip Series Damping Resistors
- Integrated RC PLL Loop Filter Eliminates the Need for External Components

description

The CDCVF2505 is a high-performance, low-skew, low-jitter, phase-lock loop (PLL) clock driver. It uses a PLL to precisely align, in both frequency and phase, the output clocks (1Y[0–3] and CLKOUT) to the input clock signal (CLKIN). The CDCVF2505 operates at 3.3 V. It also provides integrated series-damping resistors that make it ideal for driving point-to-point loads.

One bank of five outputs provides low-skew, low-jitter copies of CLKIN. Output duty cycles are adjusted to 50 percent, independent of duty cycle at CLKIN. The device automatically goes in power-down mode when no input signal is applied to CLKIN.

Unlike many products containing PLLs, the CDCVF2505 does not require an external RC network. The loop filter for the PLLs is included on-chip, minimizing component count, space, and cost.

Because it is based on the PLL circuitry, the CDCVF2505 requires a stabilization time to achieve phase lock of the feedback signal to the reference signal. This stabilization is required following power up and application of a fixed-frequency, fixed-phase signal at CLKIN, and following any changes to the PLL reference.

The CDCVF2505 is characterized for operation from -40°C to 85°C.

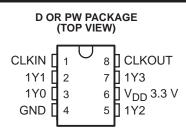


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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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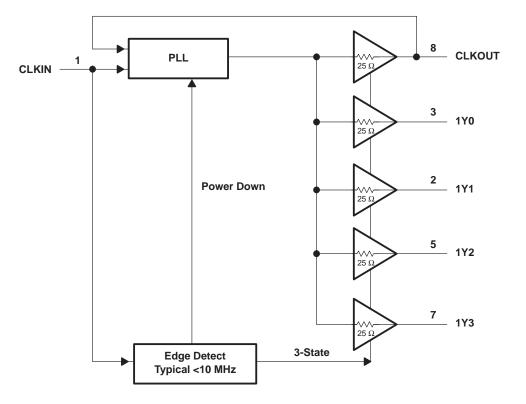


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FUNCTION TABLE					
INPUT OUTPUTS					
CLKIN	1Y (0:3) CLKOUT				
L	L	L			
Н	Н	Н			
<10 MHz†	Z	Z			

[†] Typically, below 2 MHz the device goes in power-down mode in which the PLL is turned off and the outputs enter into Hi-Z mode. If a >10-MHz signal is applied at CLKIN the PLL turns on, reacquires lock, and stabilizes after approximately 100 μ s. The outputs will then be enabled.

functional block diagram





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TERMINAL							
NAME	NO.	I/O	DESCRIPTION				
1Y[0–3]	2, 3, 5, 7	0	Clock outputs. These outputs are low-skew copies of CLKIN. Each output has an integrated $25 \cdot \Omega$ series damping resistor.				
CLKIN	1	I	Clock input. CLKIN provides the clock signal to be distributed by the CDCVF2505 clock driver. CLKIN is used to provide the reference signal to the integrated PLL that generates the clock output signals. CLKIN must have a fixed frequency and fixed phase for the PLL to obtain phase lock. Once the circuit is powered up and a valid signal is applied, a stabilization time (100 μ s) is required for the PLL to phase lock the feedback signal to CLKIN.				
CLKOUT	8	0	Feedback output. CLKOUT completes the internal feedback loop of the PLL. This connection is made inside the chip and an external feedback loop should NOT be connected. CLKOUT can be loaded with a capacitor to achieve zero delay between CLKIN and the Y outputs.				
GND	4	Power	Ground				
V _{DD3.3V}	6	Power	3.3-V Supply				

Terminal Functions

absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

Supply voltage range, V _{DD}		. –0.5 V to 4.3 V
Input voltage range, V _I (see Notes 1 and 2)		V to V _{DD} + 0.5 V
Output voltage range, V_O (see Notes 1 and 2) .	-0.5	V to V _{DD} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)		±50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$))	±50 mA
Continuous total output current, $I_O (V_O = 0 \text{ to } V_D)$	(סמ	±50 mA
Package thermal impedance, θ_{JA} (see Note 3):	D package	165.5°C/W
	PWR package	230.5°C/W
Storage temperature range, T _{stg}		-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This value is limited to 4.3 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}	3	3.3	3.6	V
High-level input voltage, VIH	0.7 V _{DD}			V
Low-level input voltage, VIL			0.3 V _{DD}	V
Input voltage, VI	0		V _{DD}	V
High-level output current, I _{OH}			-12	mA
Low-level output current, IOL			12	mA
Operating free-air temperature, T _A	-40		85	°C



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timing requirements over recommended ranges of supply voltage and operating free-air temperature

			MIN	NOM	MAX	UNIT
fclk	Clock frequency		24		200	MHz
		24 MHz – 85 MHz (see Note 4)	30%		85%	
	Input clock duty cycle	86 MHz – 200 MHz	40%	50%	60%	
	Stabilization time (see Note 5)				100	μs

NOTES: 4. Ensured by design but not 100% production tested.

5. Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLKIN. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	V _{DD}	MIN	TYP [†]	MAX	UNIT
VIK	Input voltage		lj = –18 mA	3 V			-1.2	V
			I _{OH} = -100 μA	MIN to MAX	V _{DD} -0.2			
∨он	High-level output voltage		I _{OH} = -12 mA	3 V	2.1			V
			$I_{OH} = -6 \text{ mA}$	3 V	2.4			
			I _{OL} = 100 μA	MIN to MAX			0.2	
VOL	VOI Low-level output voltage		I _{OL} = 12 mA	3 V			0.8	V
-			IOL = 6 mA	3 V			0.55	
			V _O = 1 V	3 V	-27			
юн	High-level output current		V _O = 1.65 V	3.3 V		-36		mA
			V _O = 2 V	3 V	27			
IOL	Low-level output current		V _O = 1.65 V	3.3 V		40		mA
lj	Input current		$V_{I} = 0 V \text{ or } V_{DD}$				±5	μA
Ci	Input capacitance		$V_{I} = 0 V \text{ or } V_{DD}$	3.3 V		4.2		pF
Co		Yn				2.8		_
	Output capacitance CLKOUT	$V_{I} = 0 V \text{ or } V_{DD}$	3.3 V		5.2		pF	

[†] All typical values are at respective nominal V_{DD} and 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 25 pF, V_{DD} = 3.3 V \pm 0.3 V (see Note 5)

	PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
^t pd	Propagation delay (normalized (see Figure 3)	CLKIN to Yn, f= 66 MHz to 200 MHz	-150		150	ps
t _{sk(o)}	Output skew (see Note 6)	Yn to Yn			150	ps
		f = 66 MHz to 200 MHz		70	150	
^t c(jit_cc)	Jitter (cycle to cycle) (see Figure 5)	f = 24 MHz to 50 MHz		200	400	ps
odc	Output duty cycle (see Figure 4)	f = 24 MHz to 200 MHz at 50% V _{DD}	45%		55%	
t _r	Rise time	$V_{O} = 0.4 V \text{ to } 2 V$	0.5		2	ns
t _f	Fall time	$V_{O} = 2 V \text{ to } 0.4 V$	0.5		2	ns

[†] All typical values are at respective nominal V_{DD} and 25°C.

NOTE 6: The t_{sk(0)} specification is only valid for equal loading of all outputs.



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ESD information

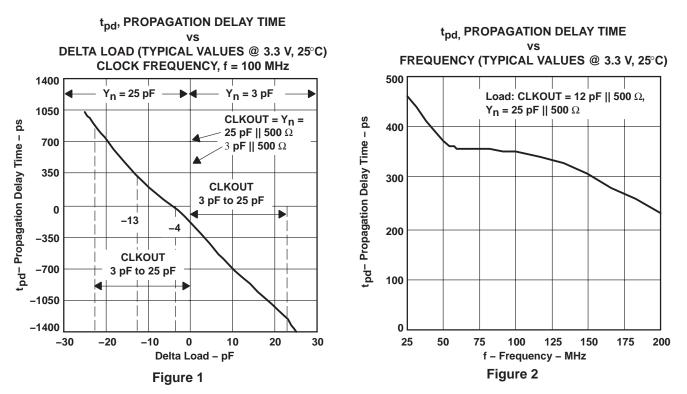
ESD MODELS	LIMIT
Human Body Model (HBM)	2.0 kV
Machine Model (MM)	300 V
Charge Device Model (CDM)	1 kV

thermal information

				THERMAL AIR FLOW (CFM)				
CDCVF2505 8-PIN SOIC			0	150	250	500	UNIT	
$R_{\theta JA}$	High K		97	87	83	77	°C/W	
$R_{\theta JA}$	Low K		165	126	113	97	°C/W	
$R_{\theta JC}$	High K	39					°C/W	
$R_{\theta JC}$	Low K	42					°C/W	

				THERMAL AIR FLOW (CFM)				
CDCVF2505 8-PIN TSSOP			0	150	250	500	UNIT	
$R_{\theta JA}$	High K		149	142	138	132	°C/W	
$R_{\theta JA}$	Low K		230	185	170	150	°C/W	
R _{0JC}	High K	65					°C/W	
$R_{\theta JC}$	Low K	69					°C/W	

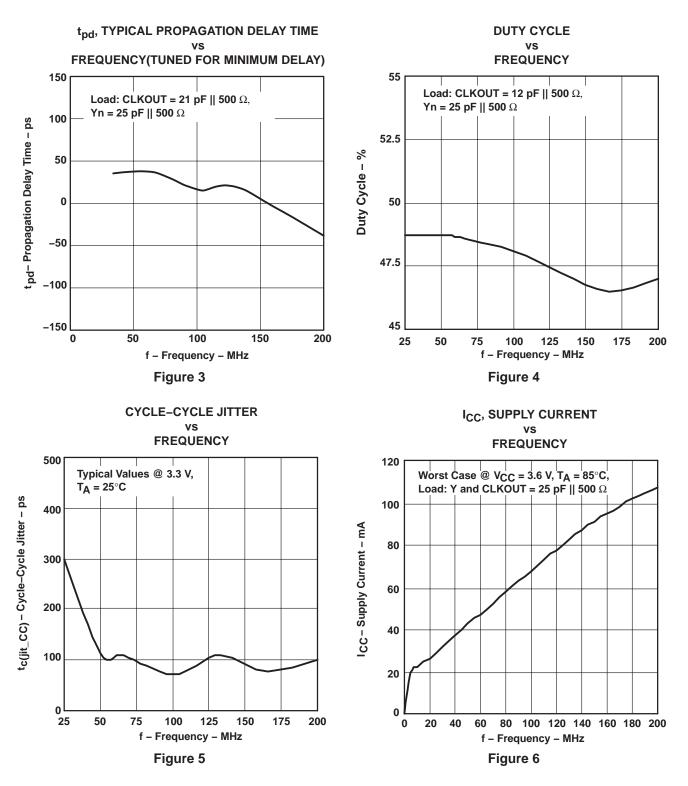
TYPICAL CHARACTERISTICS



NOTE: Delta Load = CLKOUT Load - Yn Load



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PARAMETER MEASUREMENT INFORMATION

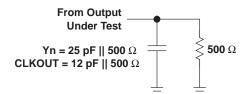


Figure 7. Test Load Circuit

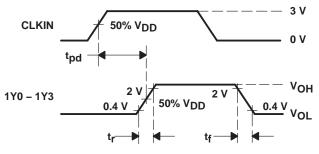


Figure 8. Voltage Threshold for Measurements, Propagation Delay (tpd)

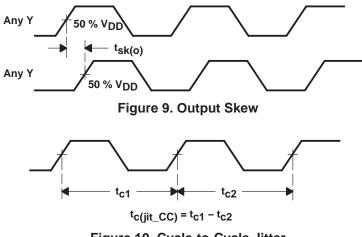


Figure 10. Cycle-to-Cycle Jitter



D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AA.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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